# NOTES (UNLESS OTHERWISE SPECIFIED):

- 1) PCB IS 2-LAYER, .062" THICK,
- 2) CONSTRUCTION IS SOLDER-MASK-OVER-BARE-COPPER (SMOBC).
- 3) ACCEPTABILITY SHALL BE BASED ON IPC-A-600, CLASS 2.
- 4) THE FOLLOWING GERBER RS274X PHOTO TOOL FILES SHALL BE USED TO DEFINE ALL CIRCUIT FEATURES:

\*.GTL - TOP LAYER GERBER DATA

- \*GRI ROTTOM LAYER GERRER DATA
- \*.GTO TOP OVERLAY GERBER DATA
- \*.GTS TOP SOLDER MASK GERBER DATA
- \*.GTP TOP-SIDE SOLDER PASTE MASK
- \*GBO BOTTOM OVERLAY GERBER DATA
- \*.GBS BOTTOM SOLDER MASK GERBER DATA
- \*.GBP BOTTOM-SIDE SOLDER PASTE MASK
- 5) THE PHOTO TOOL SHALL NOT BE COMPENSATED WITHOUT PRIOR ENGINEERING APPROVAL PCB DESIGNER; RICH LOBDILL PH (805) 880-1621 FAX (805) 961-1792.

### FABRICATION TOLERANCES

- 6) END PRODUCT CONDUCTOR WIDTHS AND PAD DIAMETERS SHALL NOT VARY MORE THAN 0.002" FROM THE 1:1 DIMENSIONS OF THE MASTER ARTWORK.
- THE CONDUCTIVE PATTERN SHALL BE POSITIONED SO THAT THE LOCATION OF ANY PAD OR LAND SHALL BE WITHIN 0.005" DIAMETER TO THE TRUE POSITION OF THE HOLE IT CIRCUMSCRBES.
- 8) ALL DRILL HOLE SIZES AND TOLERANCES APPLY AFTER PLATING.
- 9) THE MINIMUM ANNULAR RING SHALL BE 0.005".
- 10) BOW AND TWIST SHALL NOT EXCEED 0.010" PER INCH.
- 11) FOR PCB ROUTING DIMENSIONS: .XXX = +/-.005" .XX = +/-.020"

# MATERIAL

- 12) BASE MATERIAL IS FR4 EPOXY FIBERGLASS
- 13) SEE STACK-UP LEGEND FOR COPPER CLADDING CALL OUTS

- 14) ALL HOLES AND CONDUCTIVE SURFACES SHALL BE PLATED WITH A MINIMUM OF 0.001" COPPER. 15) AFTER SOLDERMASK, ALL EXPOSED HOLES AND CONDUCTIVE SURFACES SHALL BE COATED
- WITH A GOLD IMMERSION PLATING TO PRESERVE SOLDERABILITY.

- 16) THE SOLDERMASK SHALL BE BLACK LIQUD PHOTO-MAGEABLE PER PC-SM-840, TYPE-B, CLASS 2.
  17) THE SOLDERMASK REGISTRATION ALLOWANCE IS 0.003". THERE SHALL BE NO SOLDERMASK ON
- ANY SOLDER PAD OR LAND.

- 18) THE LEGEND SHALL BE SCREEN-PRINTED USING PERMANENT YELLOW EPOXY INK.
- 19) THE SCREEN PRINTING REGISTRATION ALLOWANCE IS 0.007". THERE SHALL BE NO INK ON ANY SOLDER PAD OR LAND.
- 20) THE VENDOR CODE AND UL FLAMMABILITY RATING MAY BE ETCHED IN THE FOIL OR MARKED IN PERMANENT EPOXY INK (VENDOR'S OPTION).

21) ALL BOARDS SHALL BE ELECTRICALLY TESTED TO THE SUPPLIED IPC-D-356A NET LIST FOR CONTINUITY, OPENS AND SHORTS.

| Layer Stack Up Detail for: 175-00026, revi, BlackFin Shorting Block.PcbDoc |                       |
|--|-----------------------|
| Layer<br>Name  | COPPER THICKNESS      |
| Top Layer (*.GTL)  | 1/2 oz, 1 oz Finished |
| Bottom Layer (*.GBL)   | 1/2 oz, 1 oz Finished |

-31.00

PRIMARY PCB SPECIFICATIONS

(REFER TO COMPLETE SPEC LISTING AT LEFT FOR FURTHER DETAILS)

NUMBER OF LAYERS -FINISHED THICKNESS .062" BASE MATERIAL FR4

GOLD IMMERSION PLATING TYPE SOLDER MASK COLOR -BLACK

NOTICE C.

THIS DRAWING EMBODES A PROPRETARY DESCIN OWNED BY LAS CHARRES 
GESERVATORY. IT IS SUBMITTED FOR A SPECIFIC PURPOSE UNDER A CONFEDERITAL RELATIONSHIP, AND EXCEPT FOR PURPOSES EMPRESSLY GRANITED. 
N WRITING, ALL ROHTS ARE RESERVED BY LAS CHARRES OBSERVATORY.

